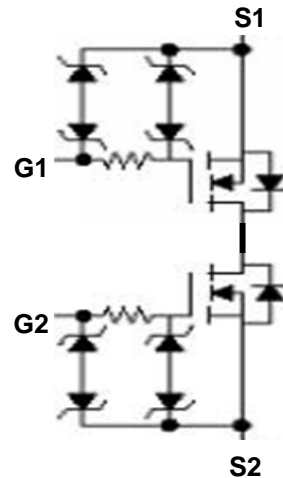
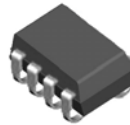


# GWS7301E – Dual 20V N-Channel Power MOSFET

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## General Description

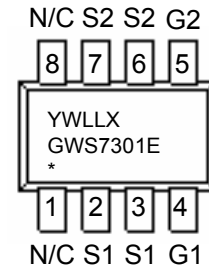
The GWS7301E is a dual low threshold gate protected MOFET designed for the small battery, cell phone, and PDA markets. Using ultra high density MOSFET process and space saving small outline J-lead package, performance normally found in a TSSOP8 footprint has been squeezed into the footprint of a TSOP6 package.



## Features

- 6.5A, 20V  $r_{DS(ON)} = 18m\Omega$  typ. at 4.5 Volts
- 5.5A, 20V  $r_{DS(ON)} = 25m\Omega$  typ. at 2.5 Volts
- Excellent thermal characteristics.
- Rated for High Electrical Overstress Performance of 15A short circuit and over current.
- Integrated gate diodes provide Electro-Static Discharge (ESD) protection of 2500V HBM.

## TSOPJW-8 Package



### Maximum Ratings and Thermal Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	10 secs	Steady State	Unit	
Drain-Source Voltage	$V_{DS}$	20		V	
Gate-Source Voltage	$V_{GS}$	$\pm 12$			
Drain Current <sup>a</sup>	$I_D$	$T_A=25^\circ\text{C}$	5.7	4.6	A
		$T_A=70^\circ\text{C}$	4.6	3.5	
Pulsed Drain Current	$I_{DM}$	30			
Maximum Power Dissipation <sup>a</sup>	$P_D$	$T_A=25^\circ\text{C}$	1.3	0.83	W
		$T_A=70^\circ\text{C}$	0.83	0.53	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150		$^\circ\text{C}$	

### Thermal Resistance Ratings

Parameter	Symbol	Typ	Max	Unit	
Junction-to-Ambient	$R_{thJA}$	$t \leq 10$ sec	81	96	$^\circ\text{C/W}$
		Steady State	135	150	
Junction-to-Foot (Lead)	$R_{thJF}$	70	85		

<sup>a</sup> Surface Mounted on FR4 Board.

Electrical Characteristics ( $T_J = 25\text{ }^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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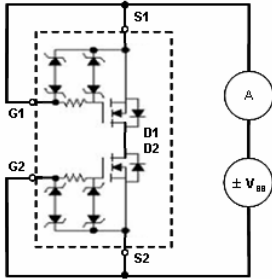
## Static

Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0V, V_{DS} = 20V$			1	$\mu A$
Gate Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = +/-12V$			+/-10	$\mu A$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.5	0.6	1.5	V
Drain-Source On-State Resistance	$r_{DS(on)}$	$V_{GS} = 4.5V, I_D = 6.5A$	11	18	25	m $\Omega$
		$V_{GS} = 2.5V, I_D = 5.5A$	15	25	35	
Source-Drain Diode Voltage	$V_{SD}$	$V_{GS} = 0, I_D = 6.5A$	0.8	1.0	1.2	V

## Dynamic

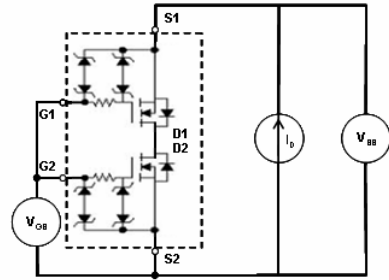
Total Gate Charge	$Q_g$	$V_{DS} = 10V, I_D = 4.0A, V_{GS} = 5.0V$		12		nC
Input Capacitance	$C_{iss}$	$V_{DS} = 20V, V_{GS} = 0V, f = 1\text{ MHz}$		870		pF
Output Capacitance	$C_{oss}$			320		
Reverse Transfer Capacitance	$C_{rss}$			240		

Test Circuit 1:  $I_{DSS}$ , Zero Gate Voltage Drain Current



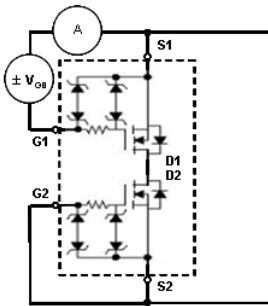
FET (1)  $I_{DSS}$ :  $V_{S2}=V_{G2}=20V, V_{S1}=V_{G1}=0V$   
 FET (2)  $I_{DSS}$ :  $V_{S1}=V_{G1}=20V, V_{S2}=V_{G2}=0V$

Test Circuit 2:  $R_{DS(ON)}$ , Drain-to-Source ON State Resistance

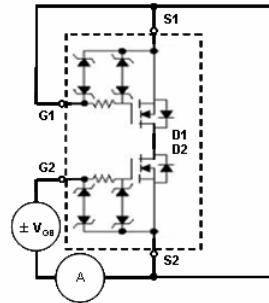


FET (1 or 2)  $R_{DS(ON)} = (V_{DS} / I_D) / 2$

Test Circuit 3:  $I_{GSS}$ , Gate Body Leakage

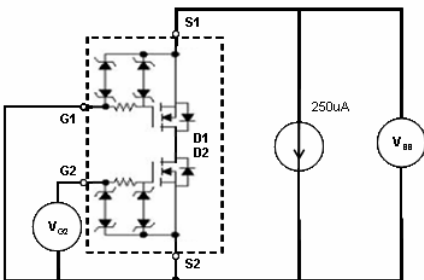


FET (1)  $I_{GSS}$ :  $V_{GS1} = \pm 12V, V_{S1}=V_{S2}=V_{G2}=0V$

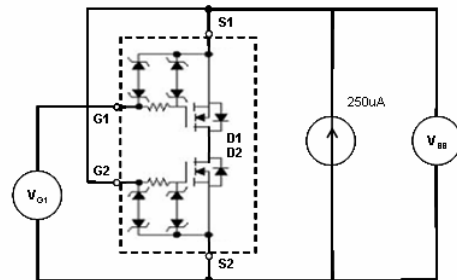


FET (2)  $I_{GSS}$ :  $V_{GS2} = \pm 12V, V_{S1}=V_{S2}=V_{G1}=0V$

Test Circuit 4:  $V_{GS(th)}$ , Gate Body Leakage

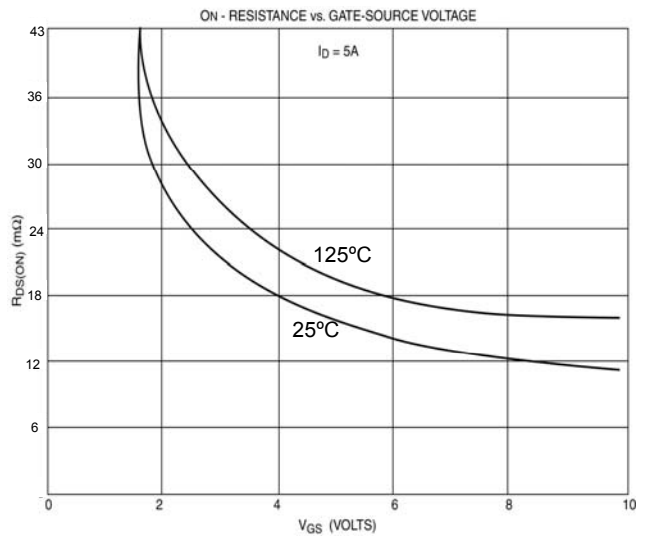
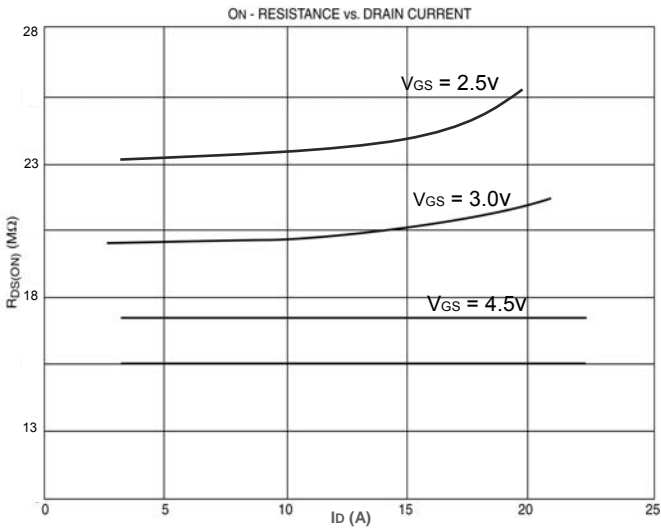
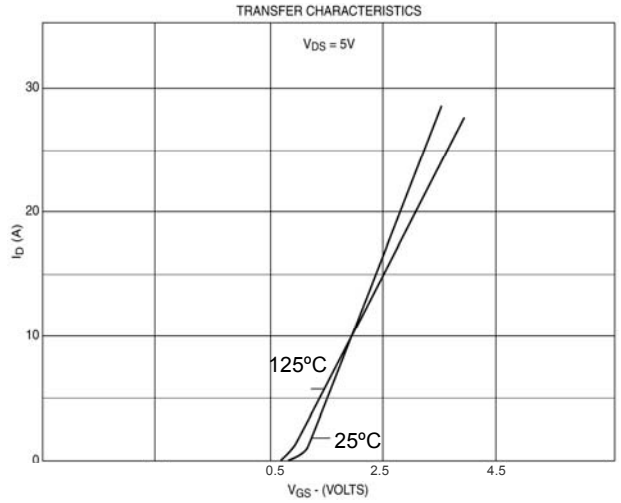
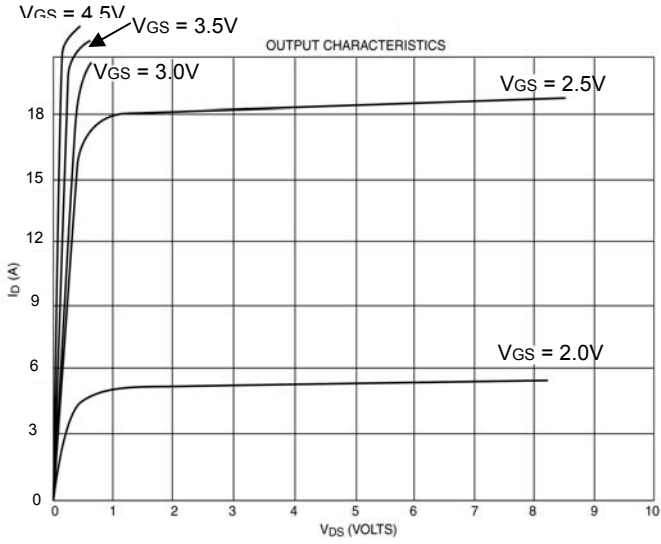


FET (1)  $V_{GS(th)1} = V_{SS}$   
 Where:  $V_{G1}=V_{S2}, V_{S1}=0V, V_{G2}=4.5V, I_{SS}=250uA$

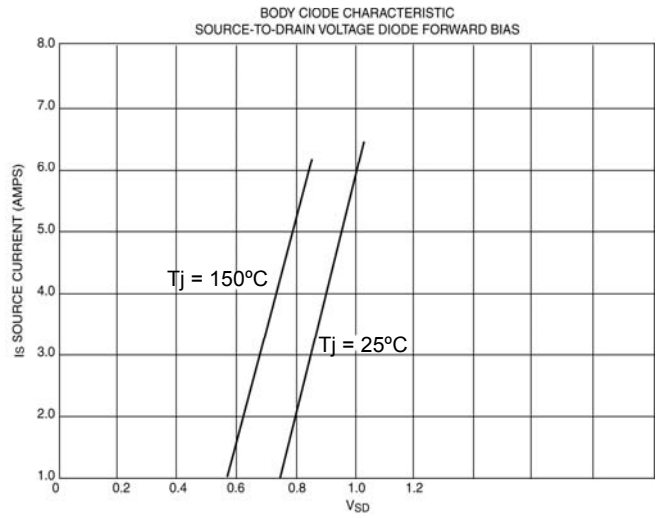
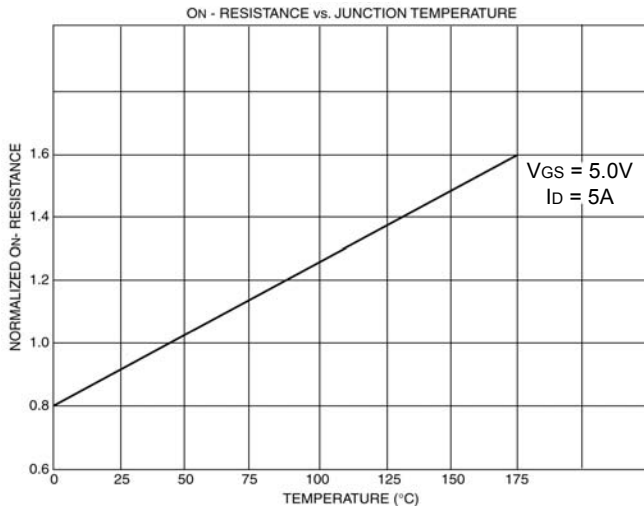
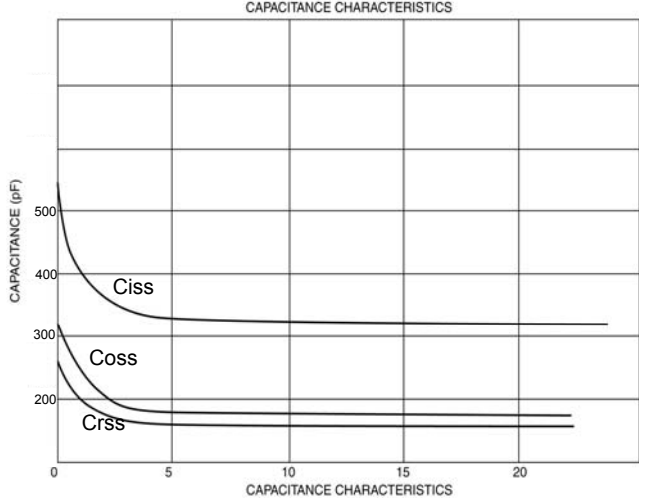
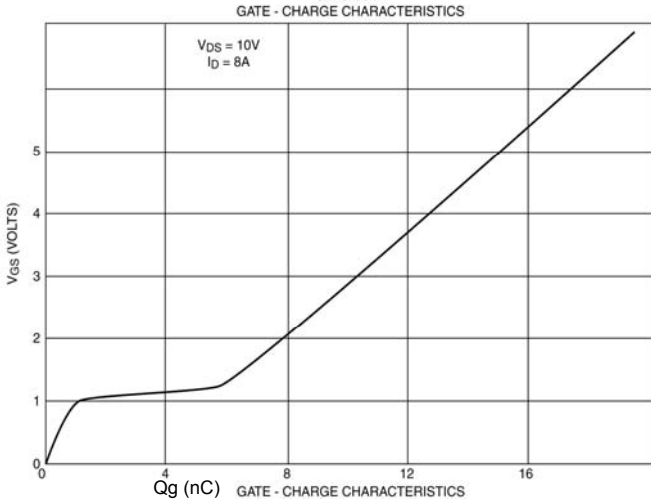


FET (2)  $V_{GS(th)2} = V_{SS}$   
 Where:  $V_{G2}=V_{S2}, V_{S1}=0V, V_{G1}=4.5V, I_{SS}=250uA$

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## Ordering Information

Package	Marking	Part Number	
		Bulk	Tape and Reel
TSOPJW-8		N/A	GWS7301EITS-T1

## Package Information

